A Formal Approach for X-PROP and Low Power Verification-based Connectivity Verification for Control-intensive Static Design Trees

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Problem Statement

- Low-power RTL simulations do not accurately predict the power consumption of the design if the simulation models used are not accurate.
- Switching power domains in presence of incorrect clock gating can be catastrophic
- The entire network fails if there is even a single failure anywhere in it because of the combinational nature. No escape route or recovery center exists.

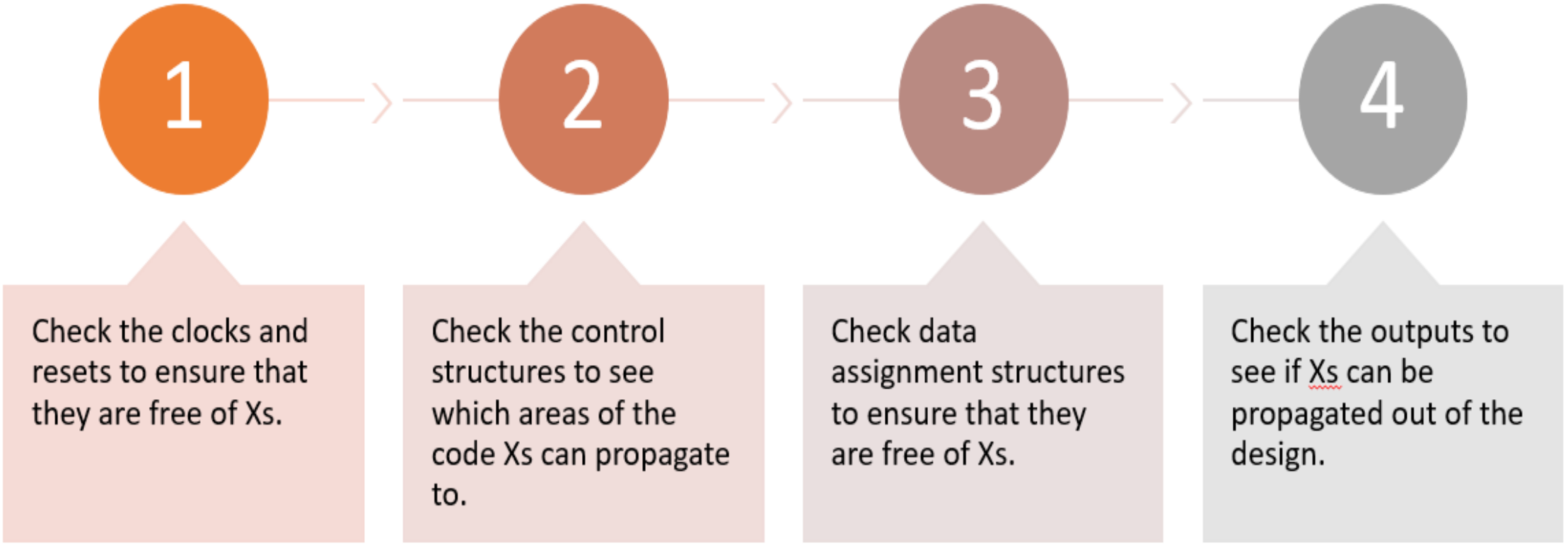
Solution Space

1) We propose a technique that combines X-PROP (Formal x-propagation) verification with integration verification
2) The standard connectivity assertions are verified while we do X-PROP verification for a power-aware design.
3) This X-PROP integration verification technique guarantees strict interface connectivity as per specification even during power state transitions.

Applications of formal Connectivity in debug domains

DFD	Design For Debug	To verify that the debugging components in the digital system are correctly connected.
DFT	Design For Test	To verify that the testing signals are correctly connected to the different components in the system.
DFM	Design for Manufacturing	To verify that the connections between the different manufacturing components in the digital system are correct.
DFX	Design for Excellence	To verify that the optimization techniques used in the system are correctly connected to the different components in the system.

Uses of VC Formal X-propagation



Advantages of VC Formal X-propagation

The tool automatically generates properties on control logic, clock, and reset such that they are free from X issues. This step guarantees completeness.

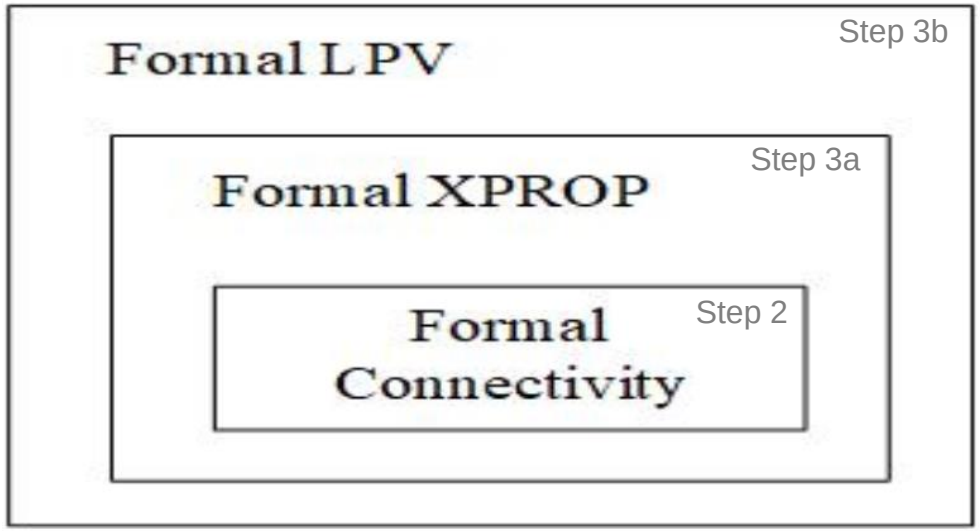
No need to create any complex testbench setup. Just need to pass the design for formal compilation and elaboration.

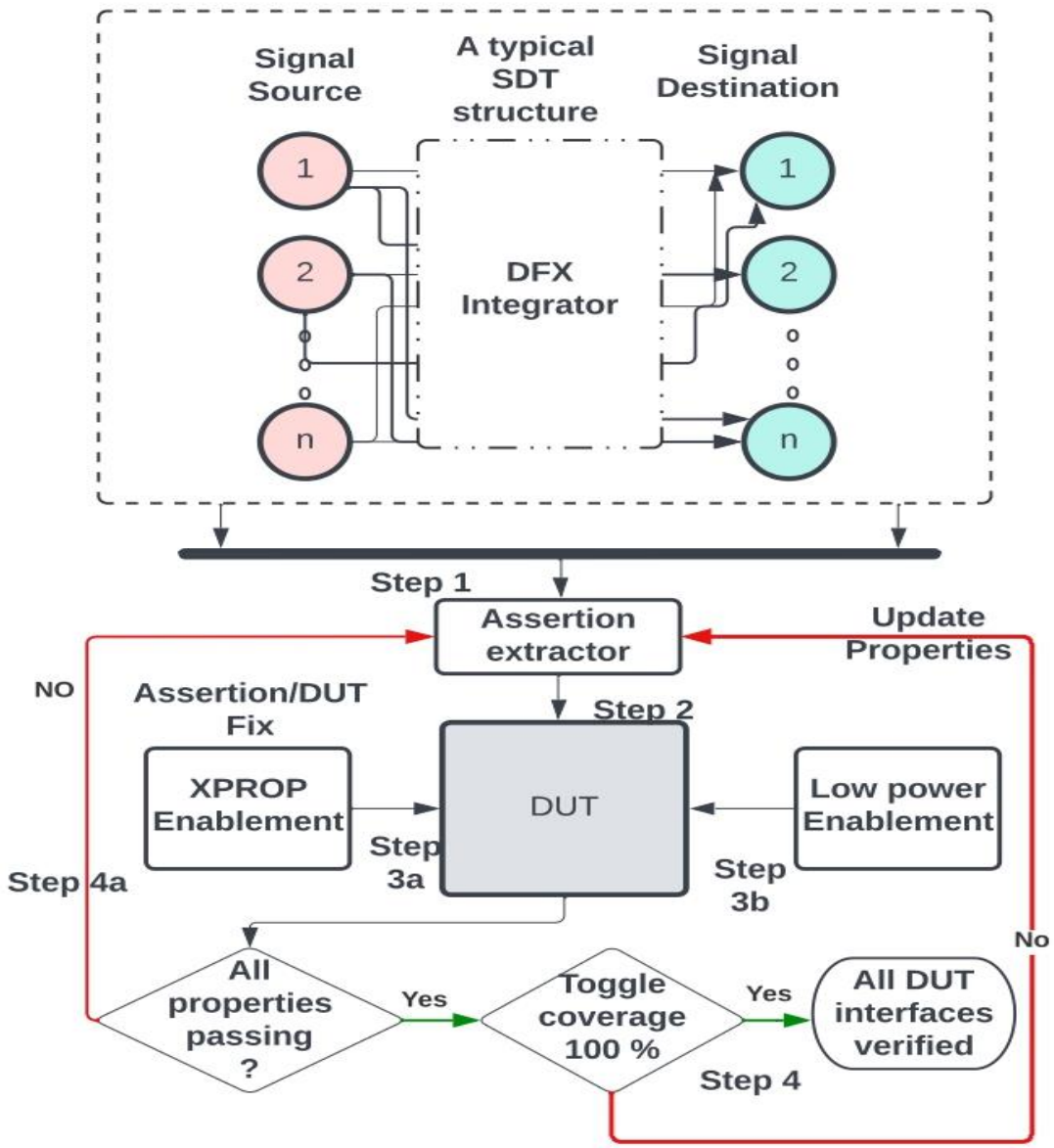
For the newly designed components, during the development stage itself, one can check if any multi-driver issues or floating ports are existing in RTL.

Since completeness is guaranteed, it is a good replacement for the Simulation-based XPROP approach, where all scenarios are difficult to generate.

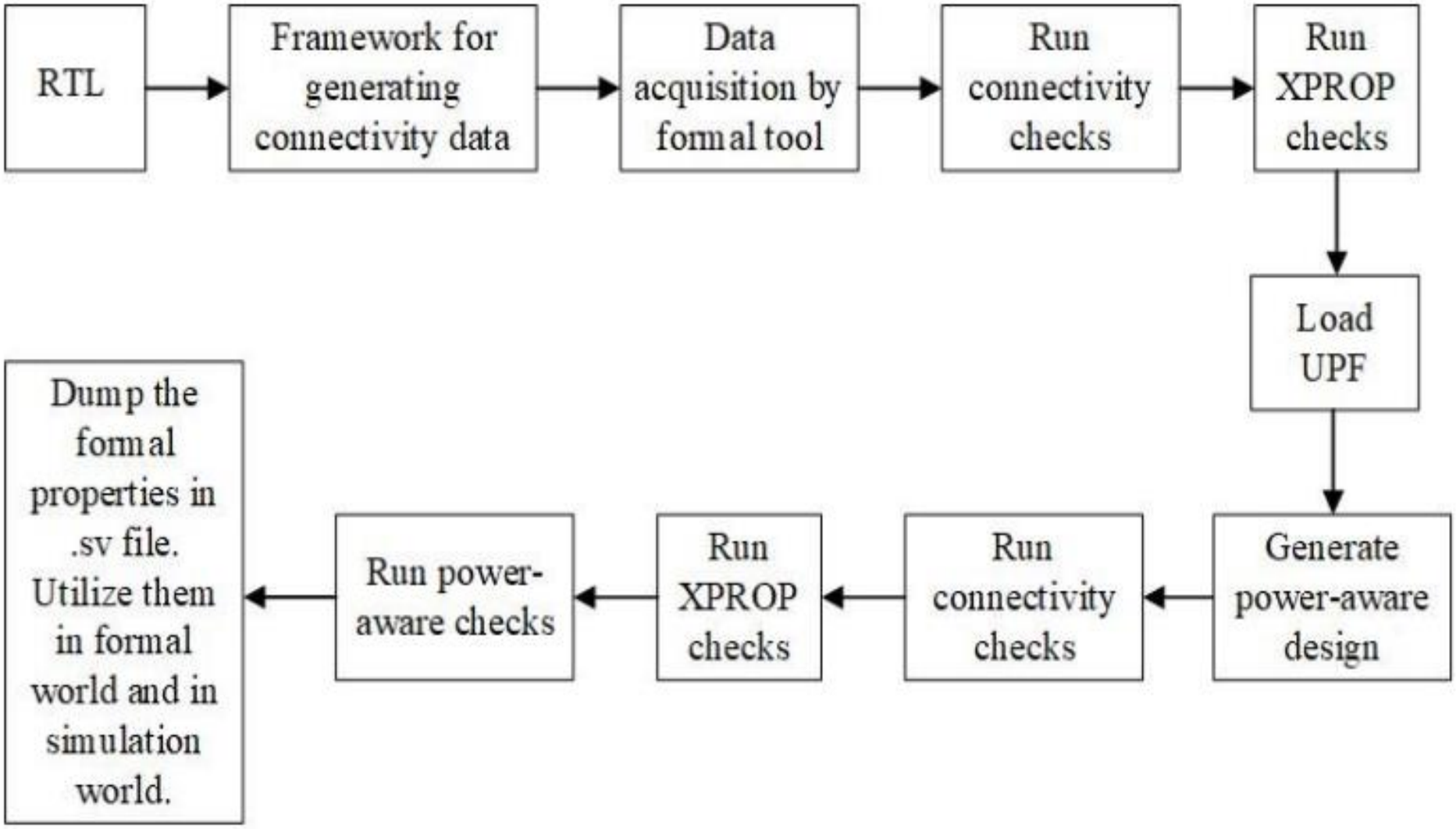
Proposed Methodology

Hierarchical based bottom-up approach

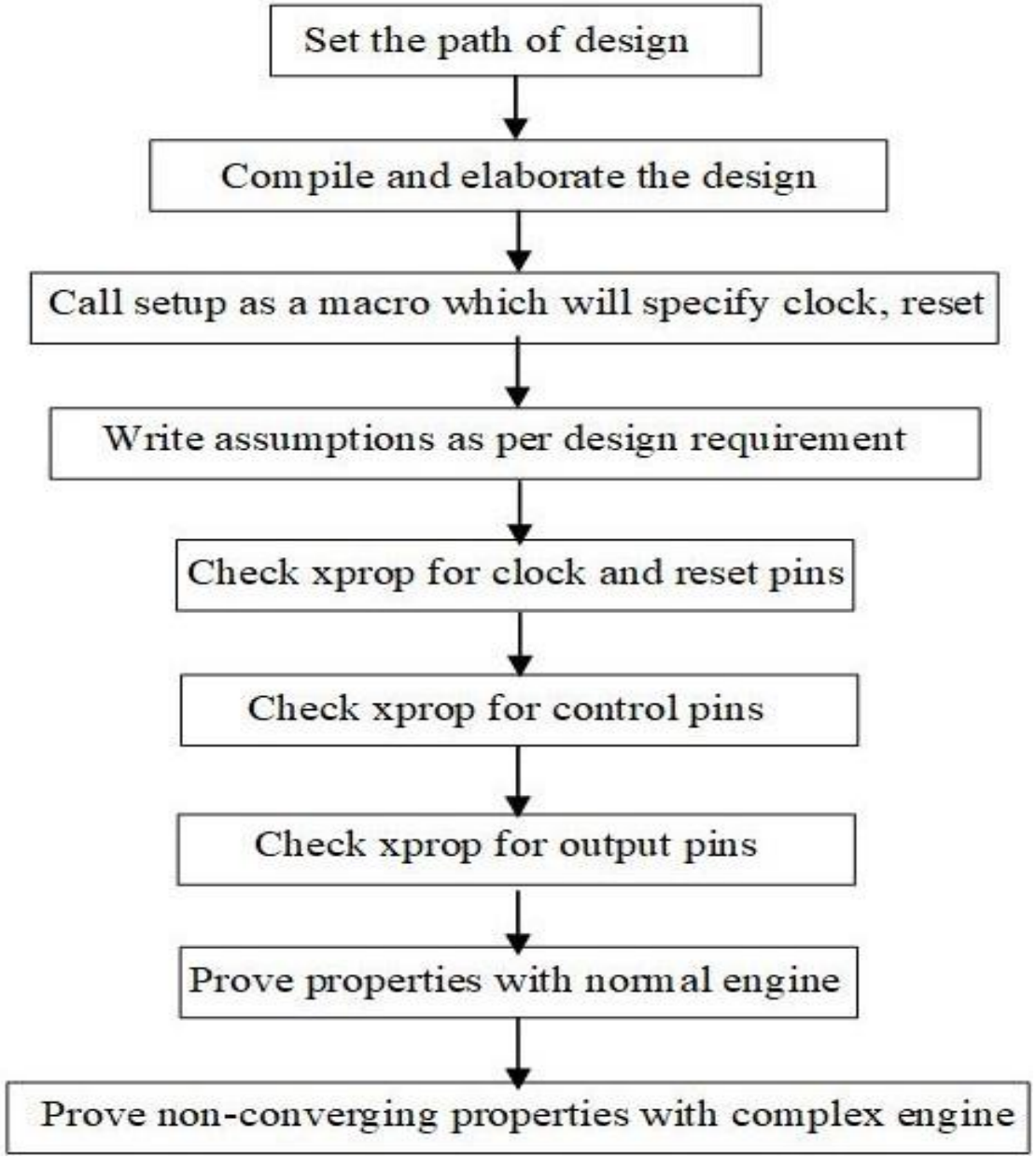




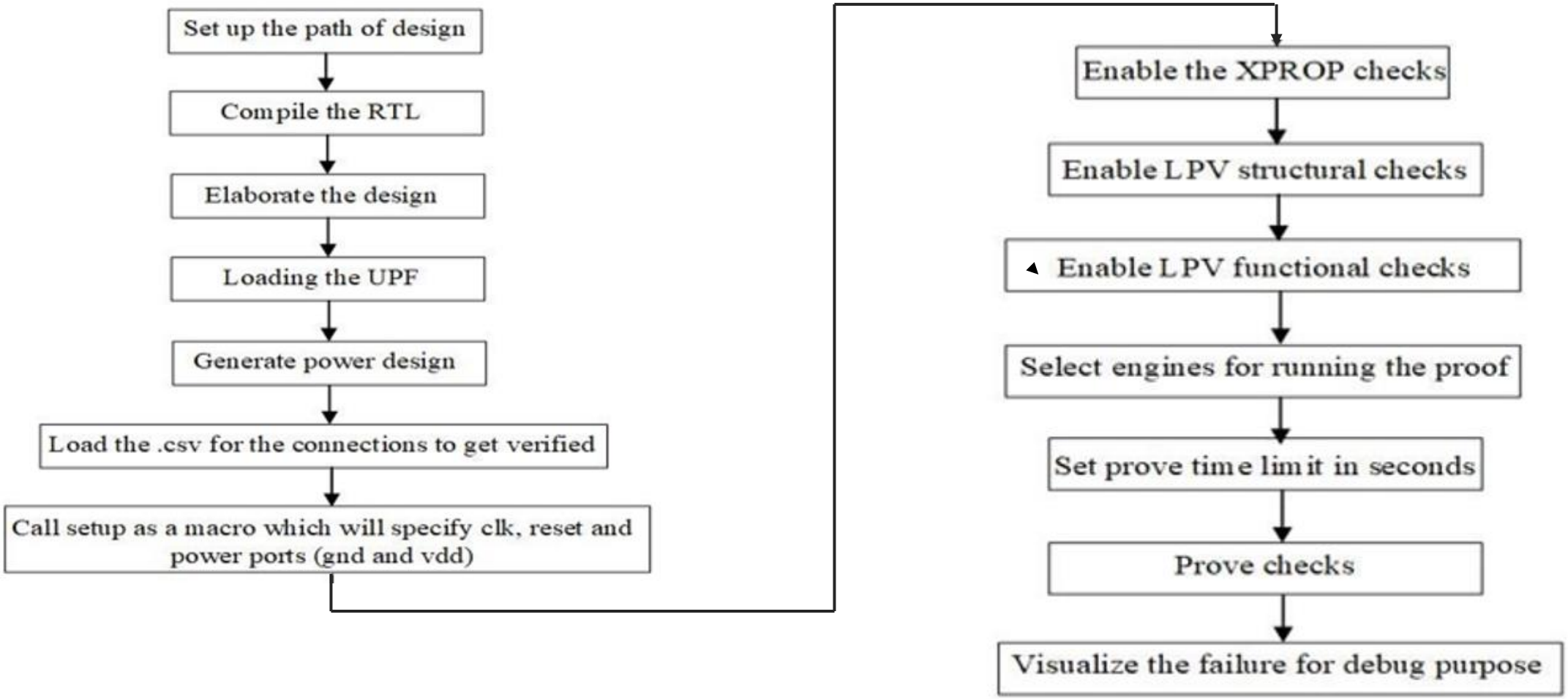
Framework for the Proposed Methodology



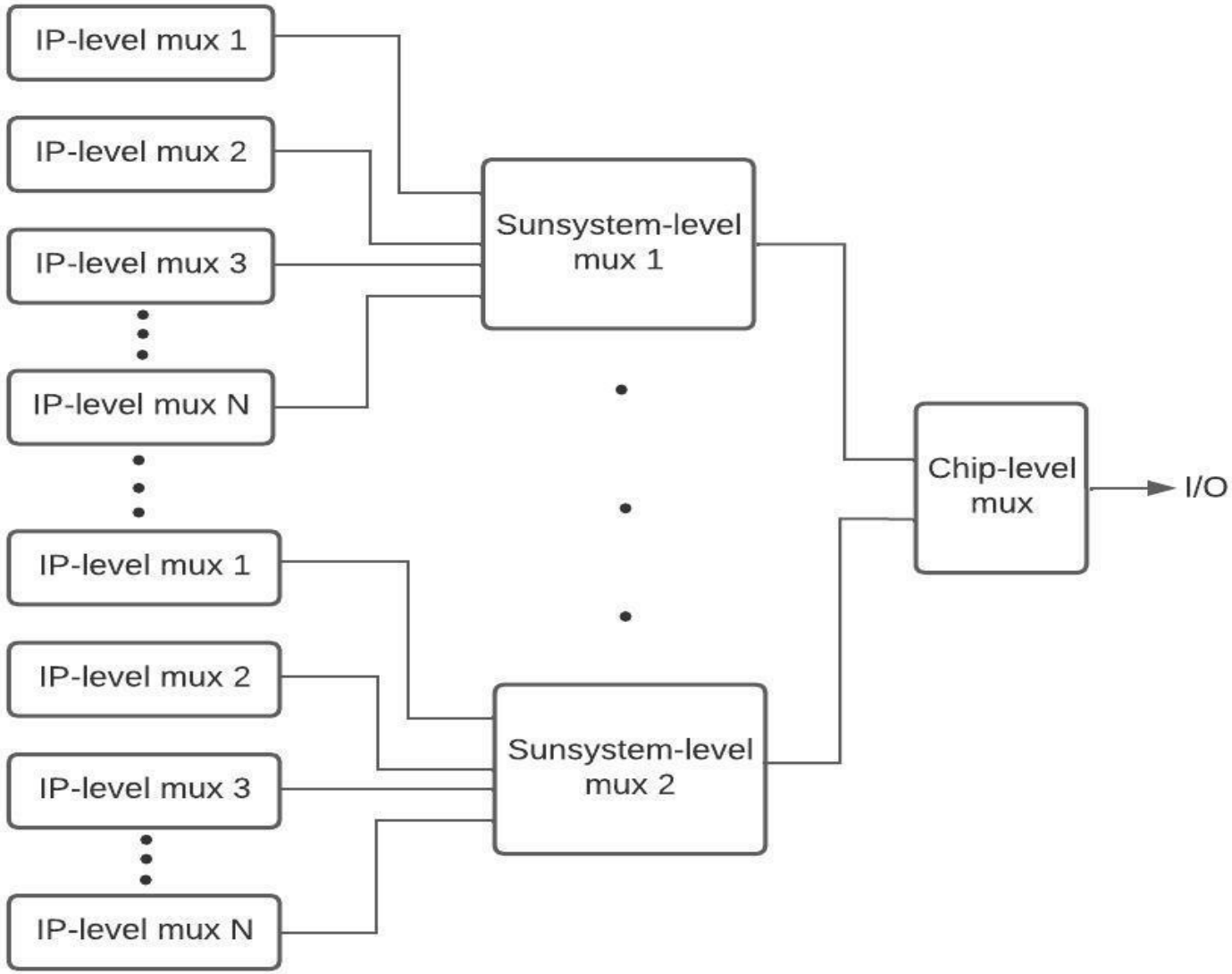
FV-based XPROP Automation Flow



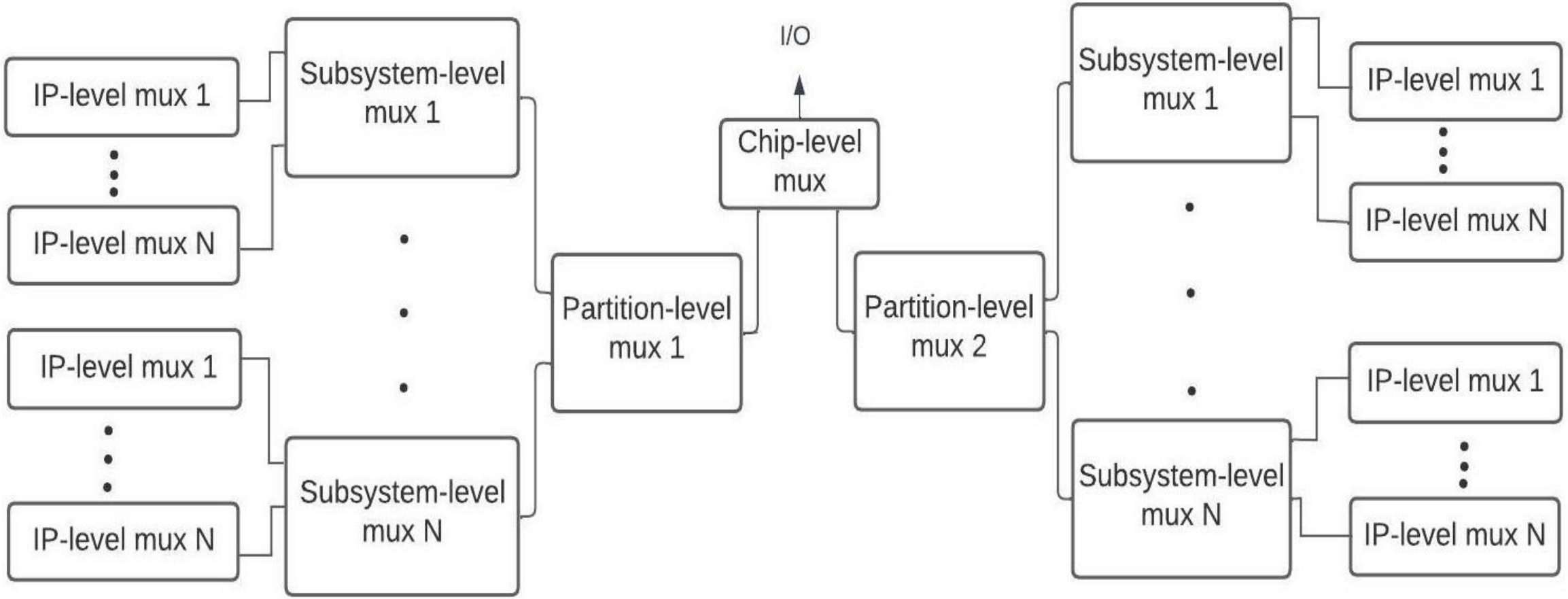
FV-based XPROP and LPV automation flow



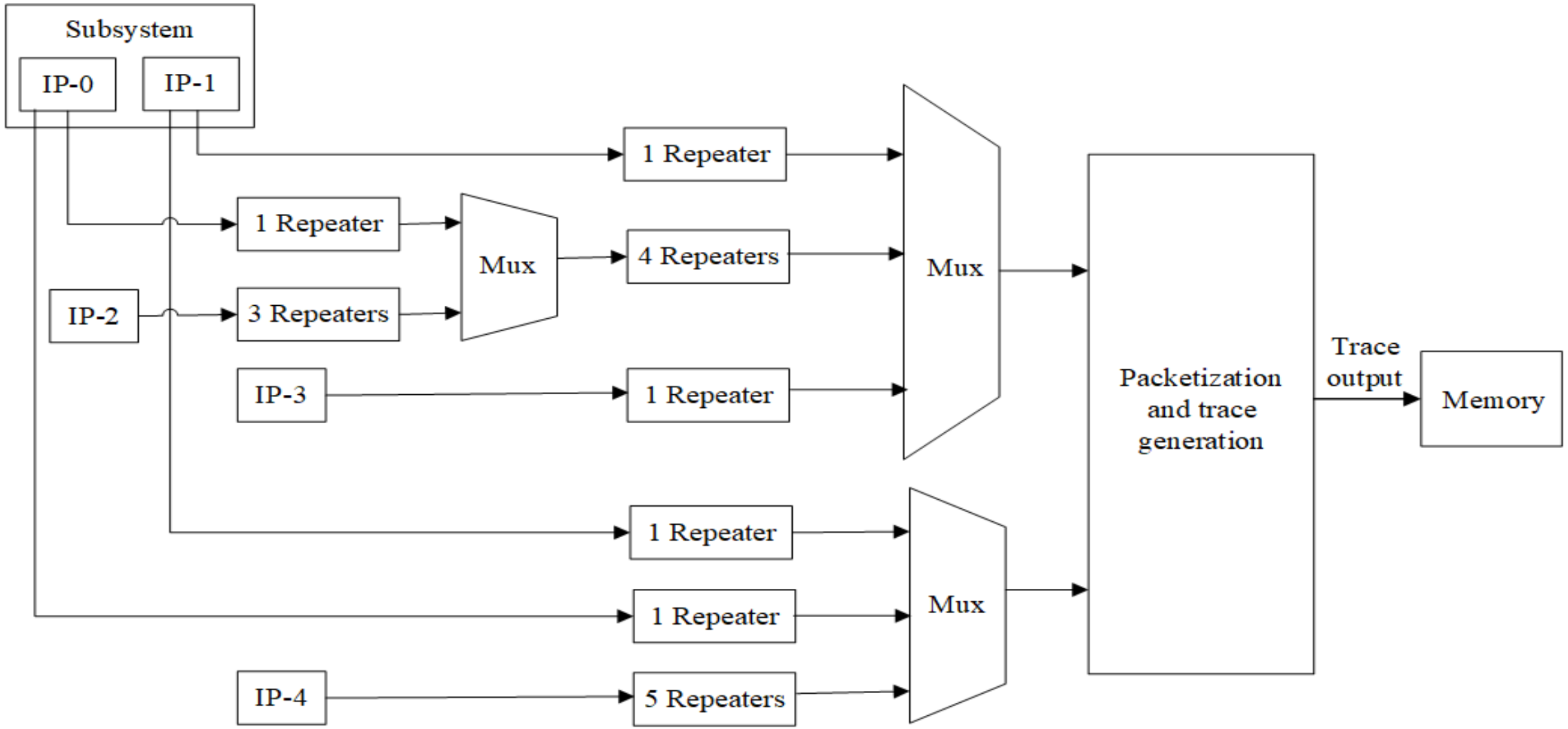
Observe-mux Tree Structure in the SoC



Partition-wise Observe-mux Tree Structure in the SoC



Observe-mux Tree Branches in the SoC along-with Repeaters for Debug Trace Generation

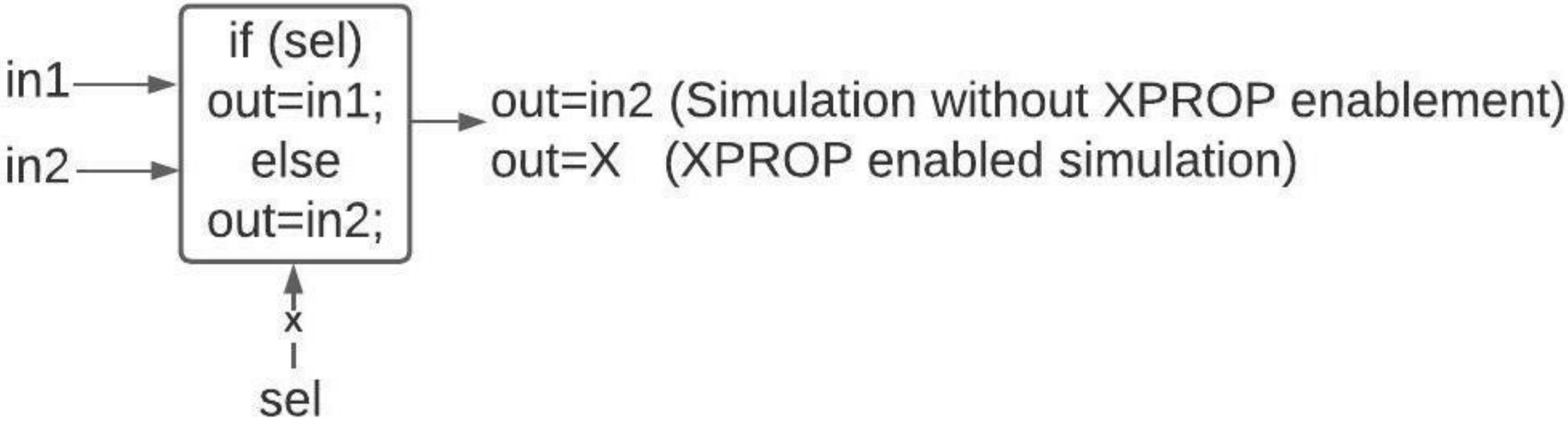


Results

X-PROP Related Bugs Detected

Output ’out’ is going ’X’ when X-PROP is enabled

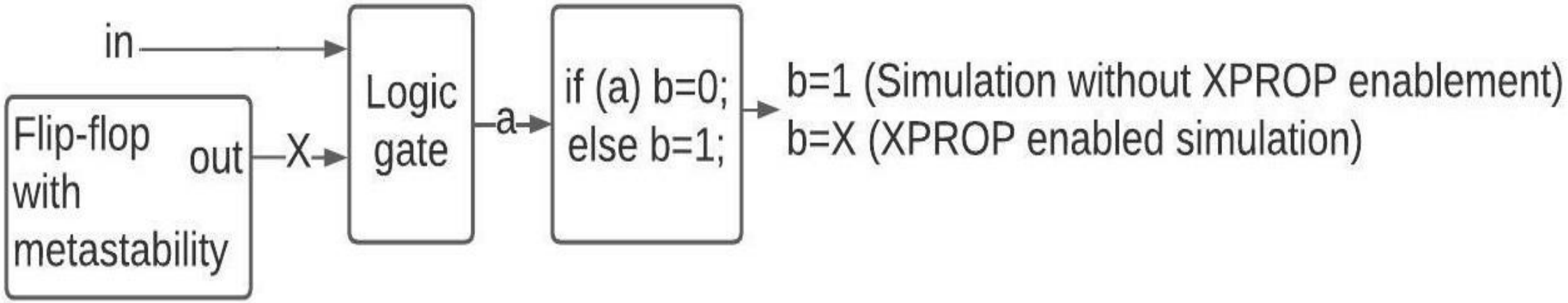
- The select line of one of the mux in the observe-mux tree was going ’X’ because of a corrupted driver.
- The output of the mux was going ’X’ with X-PROP enablement. Without X-PROP enablement, the failure was not observed because the output was ’in2’.



X-PROP Related Bugs Detected

Output ’b’ going ’X’ when X-PROP is enabled

One of the flip-flops entered the meta-stability state. This led to one of the inputs of one of the logic resulting ’X’. In X-PROP-enabled formal verification, the output of logic has gone ’X’ since the input is ’X’. In the RTL simulation without X-PROP enablement, this output was ’1’.



Turn-around Time Improvement with the Proposed Methodology

Category	Time for formal technique	Time for simulation technique	Gain
Connectivity	4hrs	20hrs	5X
Connectivity + XPROP	24hrs	50hrs	2X
Connectivity + XPROP + power-aware design	40hrs	84hrs	2.1X

Future Scope

Future work will deploy the proposed methodology, beginning with subsystems verification and moving on to whole SOC verification utilizing the divide-and-conquer method.

In the future, the proposed methodology will be applied to both the functional and debug paths.

The proposed methodology will also be used in server-based multi-die platforms to verify

- Die-to-tile connectivity
- Die-to-die connectivity
- Tile-to-tile connectivity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